

IN THE CLAIMS

Please amend claims 1 and 7 as follows:

SUB  
B1 7  
A2

1. (Amended) A semiconductor device, comprising:  
a plurality of semiconductor chips mounted on an outer surface of a substrate;  
an insulation film provided on said substrate, wherein a top surface and side surfaces of  
said plurality of semiconductor chips are encrusted in said insulation film; and  
wiring provided on said insulation film, wherein said wiring is connected to said plurality  
of semiconductor chips through a connection hole formed on said insulation film.

SUB  
B2 7  
A3

7. (Amended) A semiconductor device, comprising:  
a plurality of semiconductor chips;  
an insulation layer supporting said plurality of semiconductor chips, wherein a top surface  
and at least a portion of side surfaces of said plurality of semiconductor chips are encrusted in  
said insulation layer and a surface opposite said top surface of said plurality of semiconductor  
chips is exposed; and  
wiring provided on said insulation layer, wherein said wiring is connected to each  
semiconductor chip of said plurality of semiconductor chips through a connection hole formed  
on said insulation layer.